



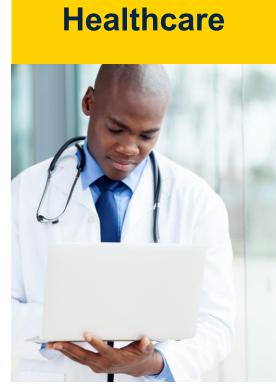
ST4SIM-300 eSIM for IoT



Dedicated to industrial & IoT applications











GSMA eSIM SGP specifications

eSIM for M2M

SGP.02

- Version 3.2 in volume production
- Version 4.3 available for 5G



- Version 2.5 in volume production
- Version 3.1 published



Technical spec SGP.32 v1.2



Introduction to GSMA for IoT specification



GSMA SGP.31/32

enables remote SIM provisioning of any IoT device



Benefits

The best of eSIM for Consumer & M2M

- Operators manage the SM-DP+ server to store and send profiles to the devices
- Remote provisioning can work on network without SMS (NB-IoT)
- No pre-integration required, like between SM-DP and SM-SR (SGP.01)
- The profile download is initiated by Service Provider (Push mechanism)
- Compatible with IoT devices that have limited functionalities (no UI)

Combined with additional benefits specific to IoT

- Provides full control to OEMs to bring connectivity into their devices
- Architecture based on interoperability, not on integrations: each player has an equal level of opportunity

ST4SIM-300 solution overview

Secure cellular connectivity solutions for IoT and Industrial



GSMA-certified eSIM for IoT solution based on SGP.32 standard specification



Complete ecosystem provided through partners eIM, IPA & bootstrap connectivity

Industrial and IoT grade solutions (T° & reliability)

Multiple package formats (Card plugin, MFF2, WLCSP)



ST4SIM-300M overview

Designed for industrial devices



Certified GSMA eSIM for IoT SGP.32 version 1.2

• Interoperable with all MNO & platform

5G

Advanced operating system

- ETSI & 3GPP Release 17 for 3G / LTE / 5G / Cat-M / NB-loT networks
- Java Card[™] & GlobalPlatform[™] compliant, including all advanced cryptography (RSA / ECC)
- Java Card[™] applets available for vertical services

Based on ST33K1M5M hardware - Certified product EAL6+

- Arm® Cortex® M35P
- Supply voltage range: 1.8 V, 3 V

Industrial-grade [-40°C, +105°C]

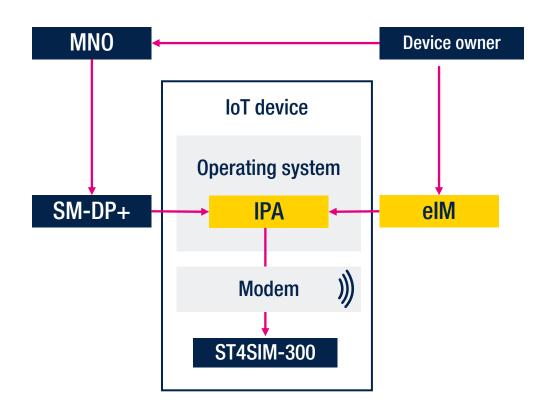
Compliant with ETSI M2M specification TS 102 671

Large choice of packages

- Standard ETSI M2M package DFN 6 x 5 mm (MFF2)
- Smallest package M2M WLCSP
- Ruggedized card body (plug-in: 2FF, 3FF, 4FF)

ST4SIM-300 ecosystem

Simplified eSIM ecosystem with the eIM and IPA



IPA – IoT Profile Assistant

- Interface between the eSIM and the eIM
- Provides functions that enable the remote provisioning
- Two possible configurations:

IPA_d
Runs on the IoT device

IPA_e
Runs on the eSIM

elM – eSIM IoT remote manager

 Provides remote interface to trigger profile management on a single IoT device or a fleet of IoT devices



ST4SIM-300 documentation

Press release

Read here



Whitepaper

Read here



Flyer

Download here



Product presentation

Download here



Campaign page





Video series Watch here





Customer journey

Localizing profiles all around the world remotely



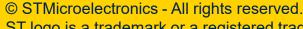


ST4SIM-300 takeaways



Our technology starts with You





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